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(12) **United States Design Patent**
Sannai et al.

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(54) **SEMICONDUCTOR DEVICE**

H05K 1/141; H05K 1/142; H05K 1/144;
H05K 1/18; H05K 1/181; H05K 1/182;
H05K 1/026

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See application file for complete search history.

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(73) Assignee: **Mitsubishi Electric Corporation,**
Tokyo (JP)

(**) Term: **15 Years**

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JP 1495189 S 4/2014

(22) Filed: **Jul. 11, 2019**

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(30) **Foreign Application Priority Data**

Mar. 29, 2019 (JP) 2019-006781

An Office Action dated by the Japanese Patent Office on Sep. 3, 2019, which corresponds to Japanese Design Application No. 2019-006781 and is related to Design U.S. Appl. No. 29/697,804.

(51) **LOC (12) Cl.** **13-03**

Primary Examiner — Elizabeth J Oswecki

(52) **U.S. Cl.**

USPC **D13/182**

(74) *Attorney, Agent, or Firm* — Studebaker & Brackett PC

(58) **Field of Classification Search**

USPC D13/182; 257/678, 684, 690, 691;
361/679.01, 713, 728, 736, 760, 761, 772,
361/775, 783, 820; 174/250, 253;
438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
H01L 2021/00; H01L 2021/02; H01L
2021/04; H01L 21/4814; H01L 21/4846;
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23/02; H01L 23/13; H01L 23/14; H01L
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2924/19042; H01L 2924/1905; H01L
2224/08054; H01L 23/58; H05B 41/14;
H02B 6/4201; G02B 6/4256; G02B
6/4257; G02B 6/4261; G02B 6/4262;
G02B 6/428; G02B 6/4281; H05K 1/14;

(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a semiconductor device showing our new design;
FIG. 2 is a rear, bottom and left side perspective view thereof;
FIG. 3 is a front view thereof;
FIG. 4 is a rear view thereof;
FIG. 5 is a top view thereof;
FIG. 6 is a bottom view thereof;

(Continued)

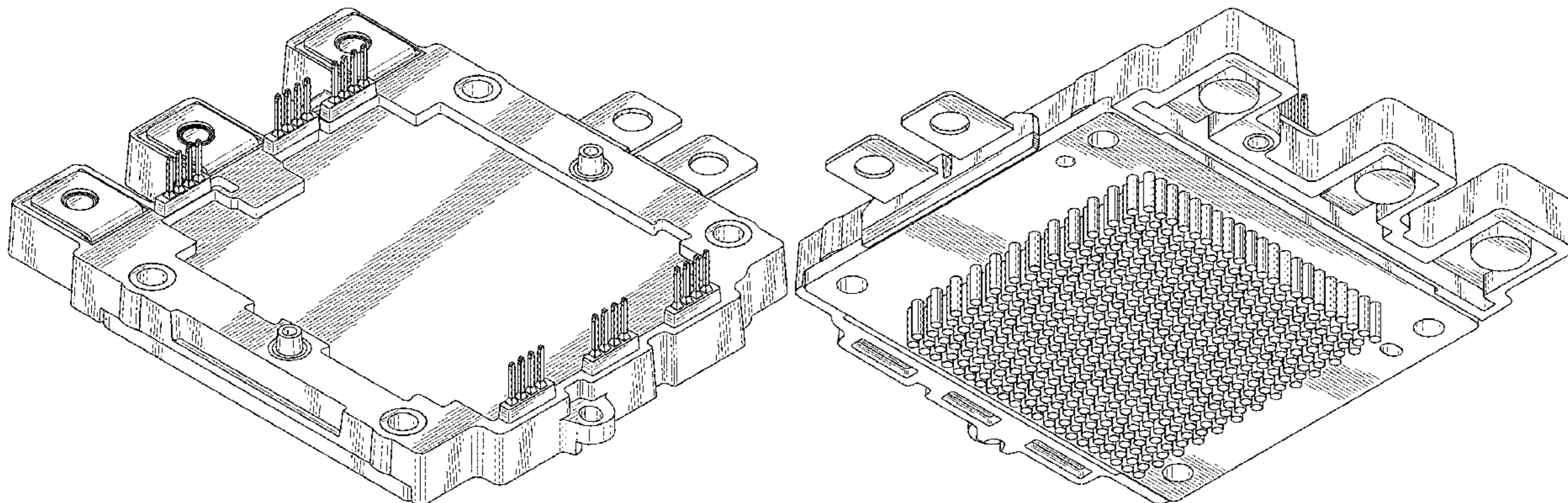


FIG. 7 is a right side view thereof; and,
FIG. 8 is a left side view thereof.

1 Claim, 8 Drawing Sheets

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FIG. 1

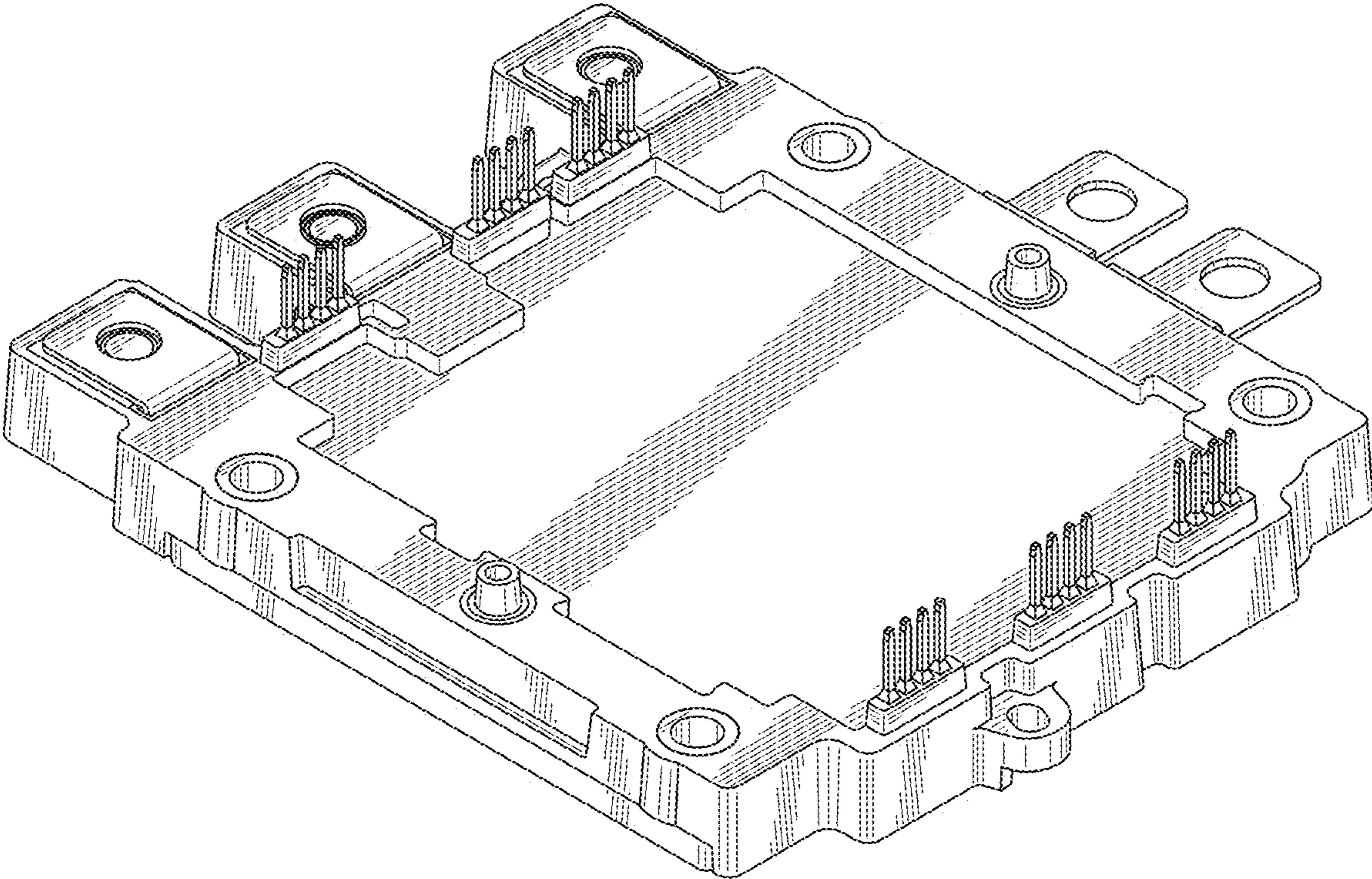


FIG. 2

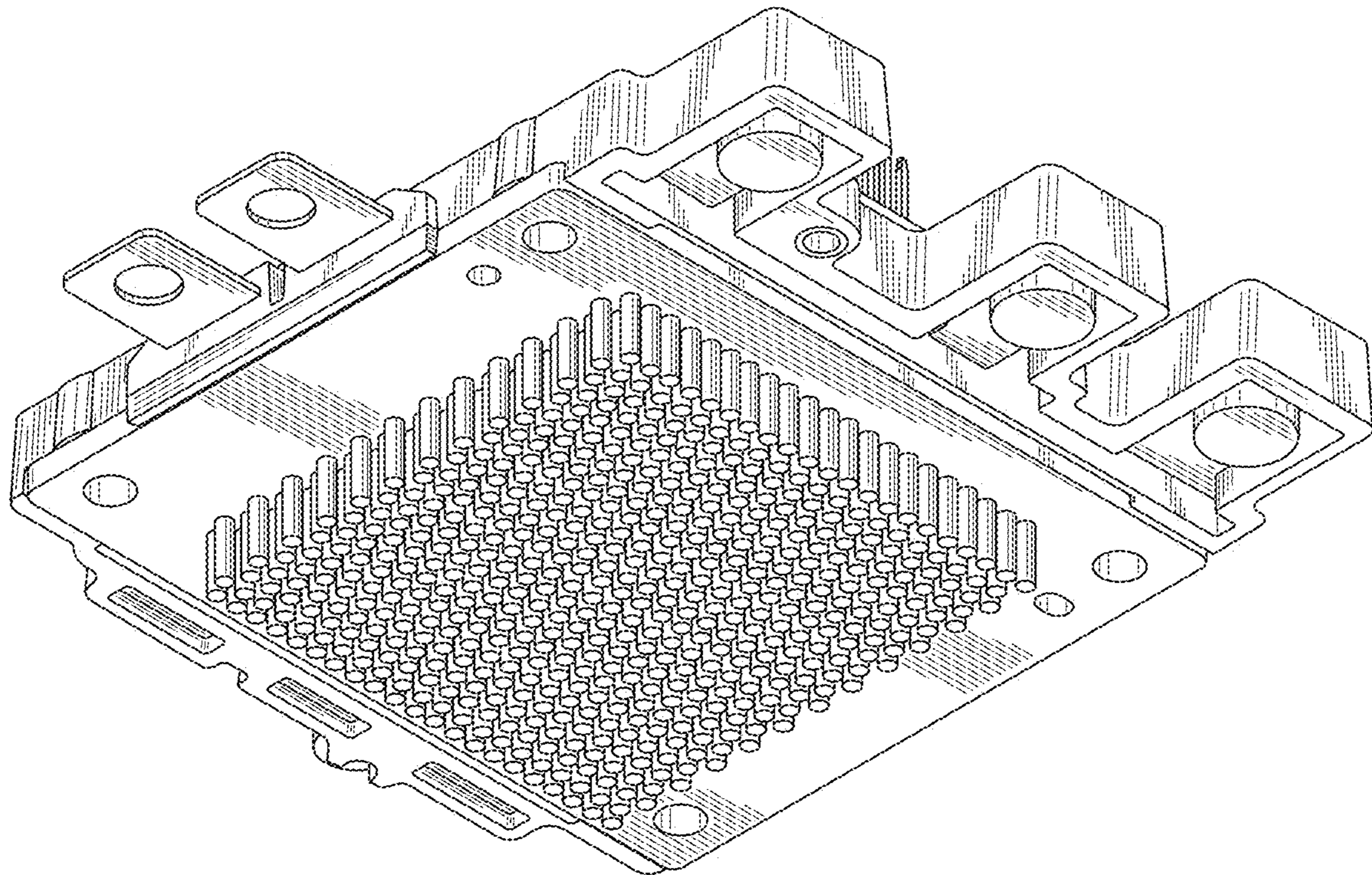


FIG. 3

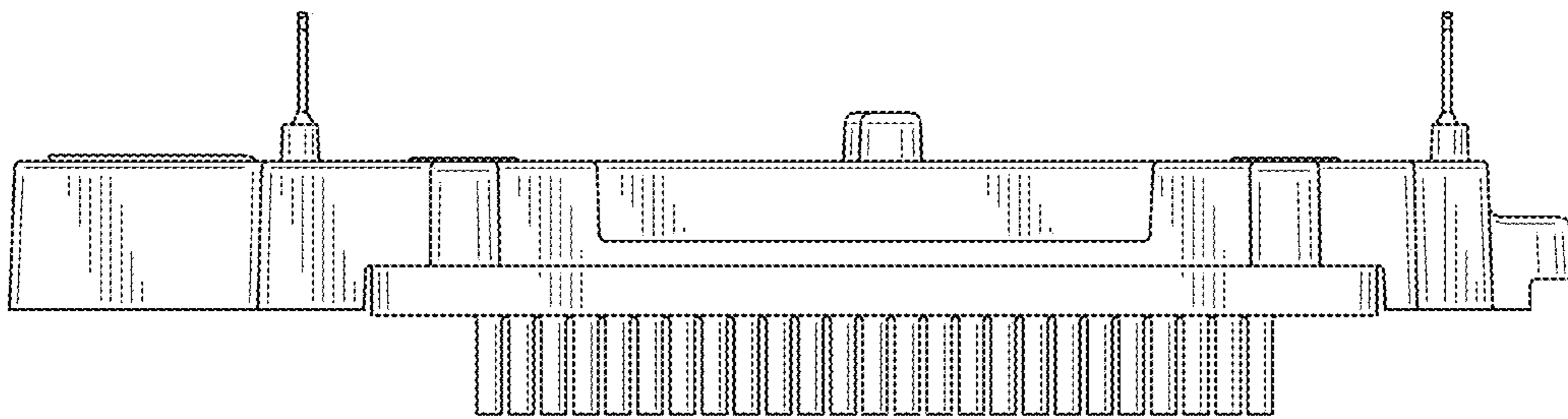


FIG. 4

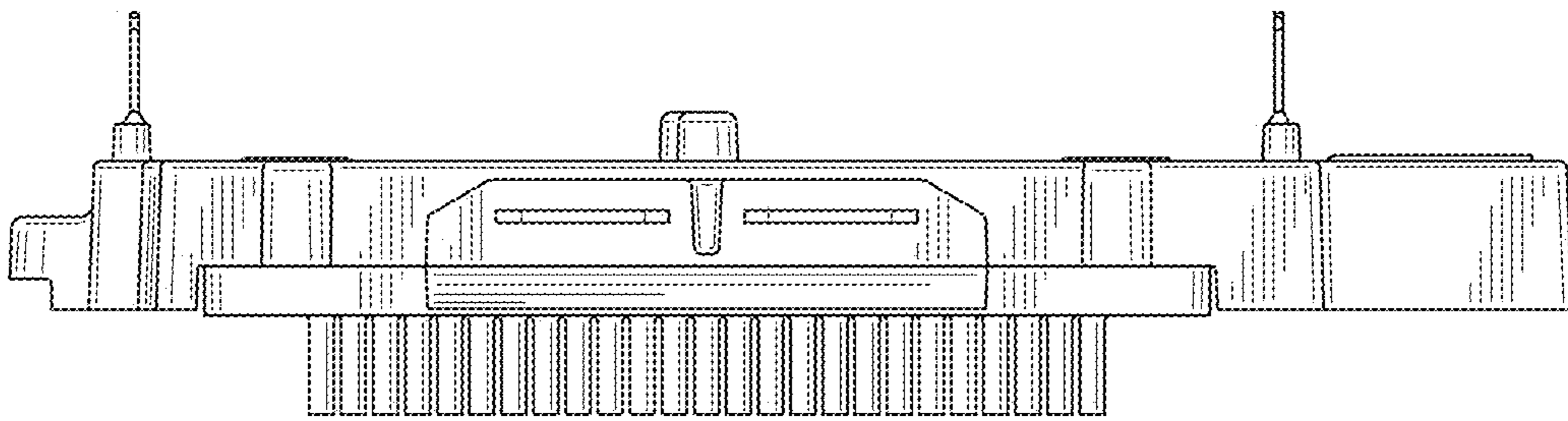


FIG. 5

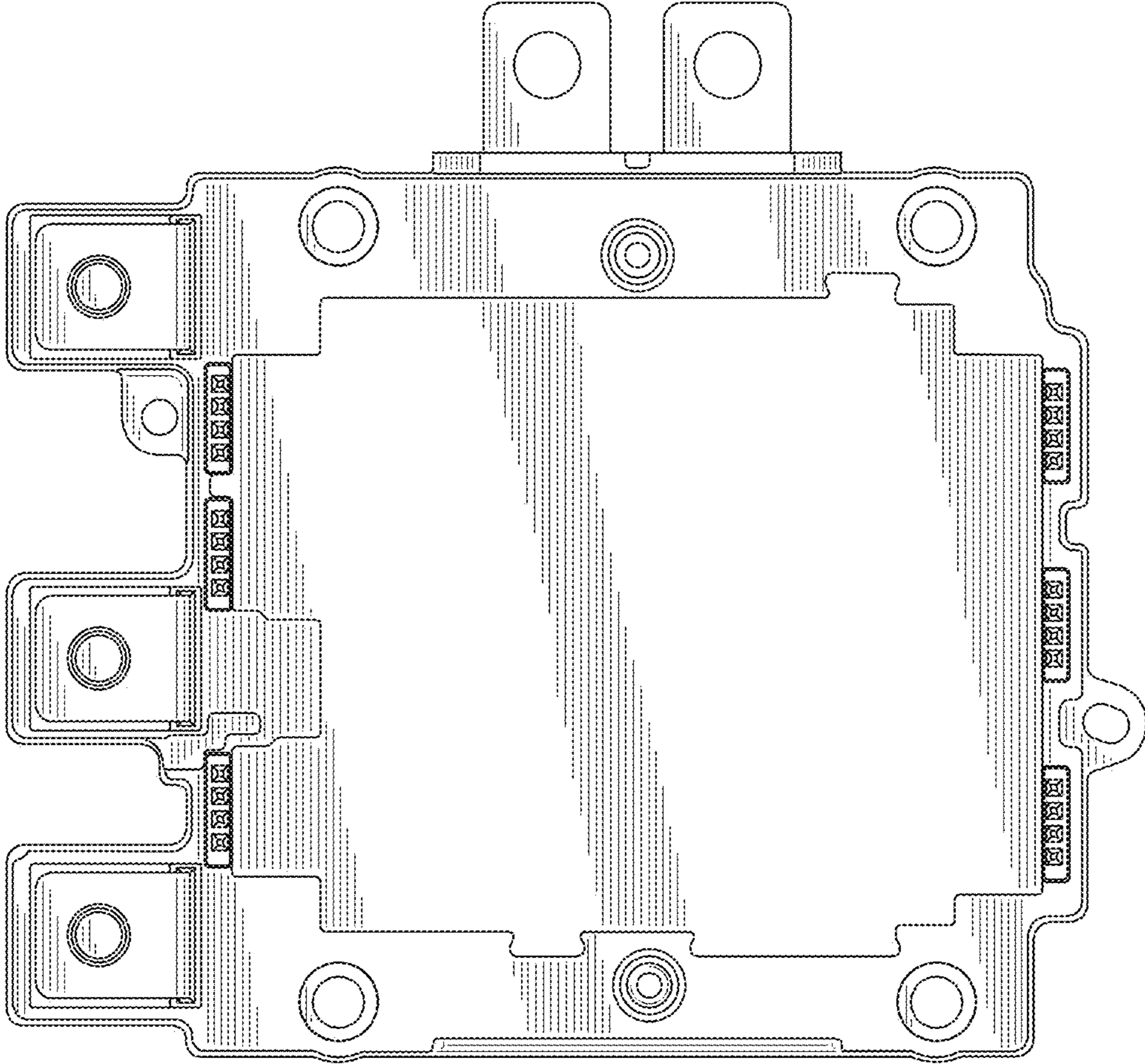


FIG. 6

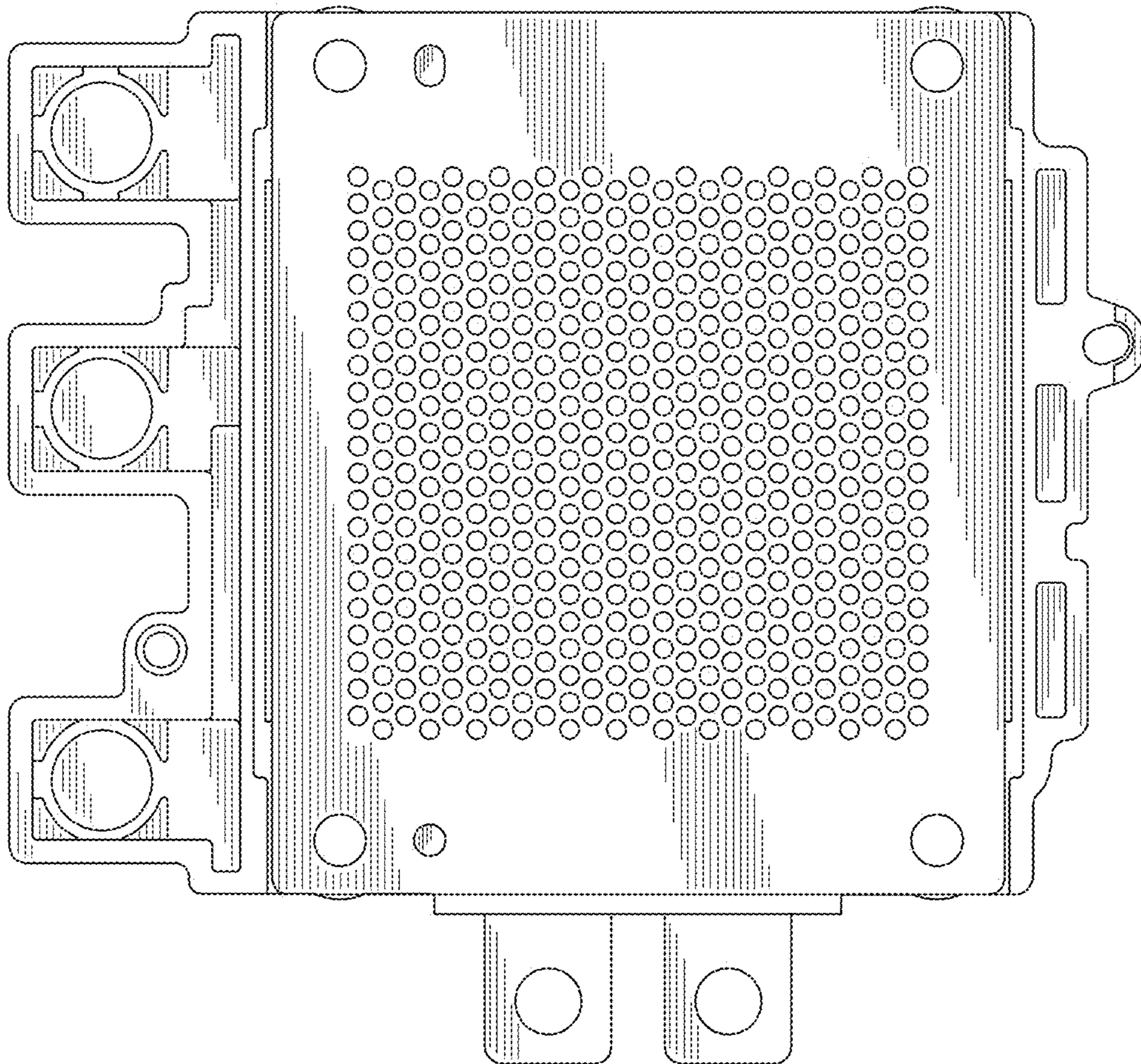


FIG. 7

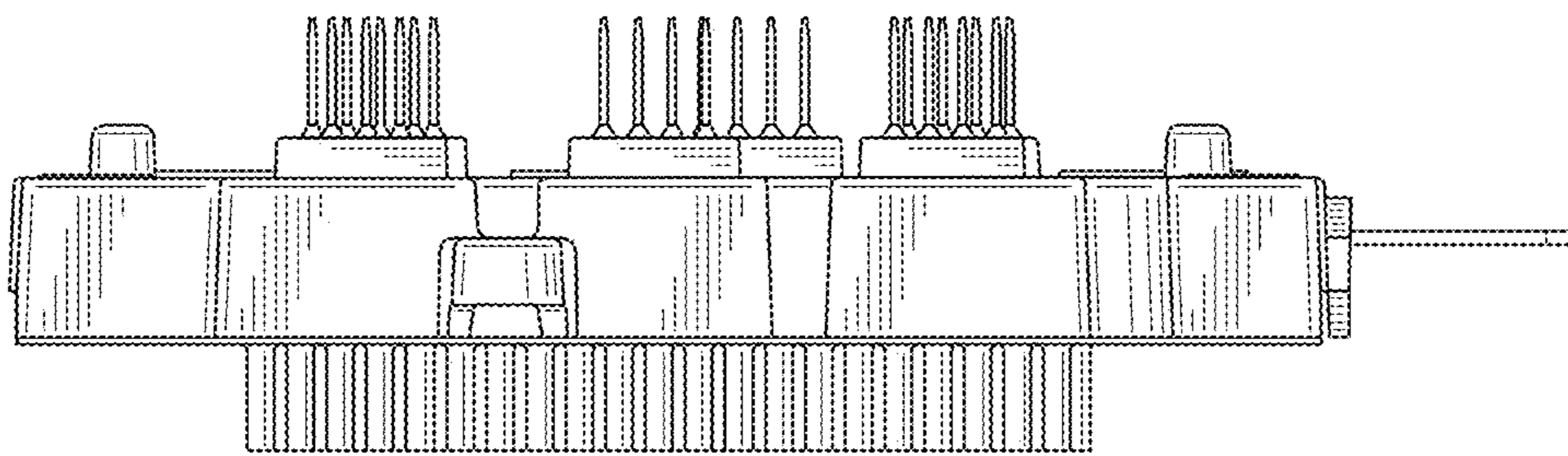


FIG. 8

